imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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140 COMMERCE DRIVE MONTGOMERYVILLE, PA 18936-1013 PHONE: (215) 631-9840 FAX: (215) 631-9855

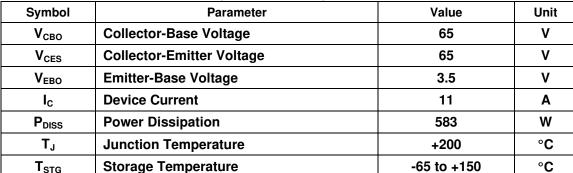
RF AND MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

Features

- Designed For High Power Pulse IFF, DME, and TACAN Applications
- 200 W (typ.) IFF 1030 1090 MHz
- 150 W (min.) DME 1025 1150 MHz
- 140 W (typ.) TACAN 960 1215 MHz
- 8.2 dB Gain
- Refractory Gold Metallization
- Ballasting And Low Thermal Resistance For Reliability
 And Ruggedness
- 20:1 Load VSWR At Specified Operating Conditions
- Input And Output Matched Common Base
 Configuration

DESCRIPTION:

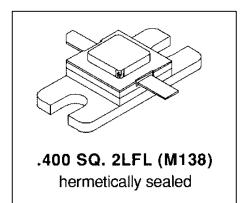
The MS2393 is a gold metallized, silicon NPN power transistor. The MS2393 is designed for applications requiring high peak power and low duty cycles such as IFF, DME and TACAN. The MS2393 is packaged in a metal/ceramic package with internal input/output matching, resulting in improved broadband performance and low thermal resistance.



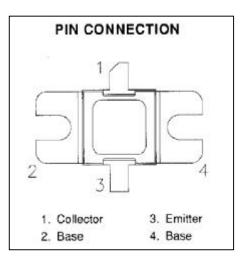
ABSOLUTEMAXIMUM RATINGS (Tcase = 25°C)

Thermal Data

R _{TH(j-c)}	Junction-Case Thermal Resistance	0.30	°C/W



MS2393





ELECTRICAL SPECIFICATIONS (Tcase = 25° C)

STATIC

Symbol		Test Conditions		Value		Units
Symbol		Test conditions	Min.	Тур.	Max.	Units
BV _{CBO}	I _c = 10 mA	I _E = 0 mA	65			V
BV _{CES}	l _c = 25 mA	$V_{BE} = 0 V$	65			V
BV _{EBO}	I _E = 5 mA	I _c = 0 mA	3.5			V
I _{CES}	V _{CE} = 50 V	l _E = 0 mA			10	mA
h _{FE}	V _{CE} = 5 V	I _c = 300 mA	5			

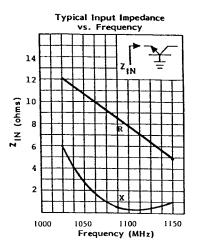
DYNAMIC

Symbol	Test Conditions		Value		Units
Symbol	Test Conditions	Min.	Тур.	Max.	Units
Pout	$f = 1025 - 1150 \text{ MHz}$ $P_{IN} = 25 \text{ W}$ $V_{CE} = 50 \text{ V}$	150			W
G₽	$f = 1025 - 1150 \text{ MHz}$ $P_{IN} = 25 \text{ W}$ $V_{CE} = 50 \text{ V}$	8.2			dB

Condition: Pulse Width = 10μ S, Duty Cycle = 1%

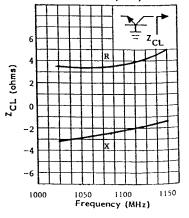
IMPEDANCE DATA

TYPICAL INPUT IMPEDANCE



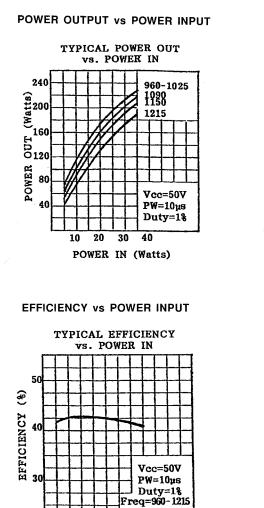
TYPICAL COLLECTOR LOAD

Typical Collector Load Impedance vs. Frequency





TYPICAL PERFORMANCE



20

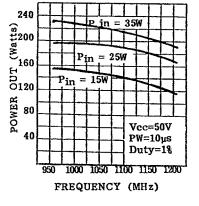
10

30 40

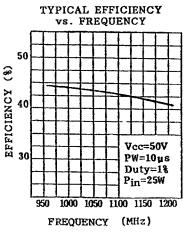
POWER IN (Watts)

POWER OUTPUT vs FREQUENCY

TYPICAL POWER OUT vs. FREQUENCY

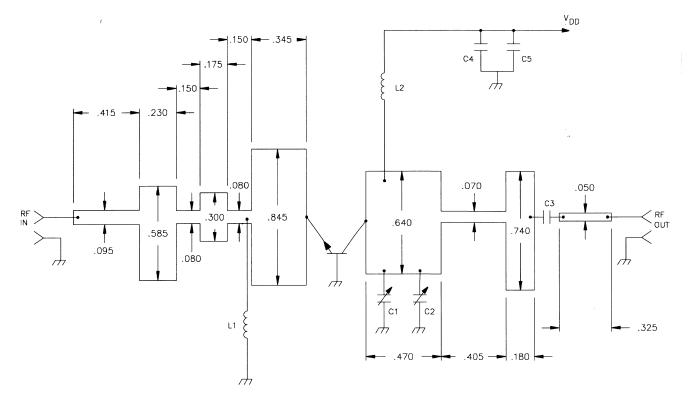


EFFICIENCY vs FREQUENCY





TEST CIRCUIT



C1, C2 : .6 - 4.5pF Gigatrim

- .0 4.3pr Gigatilit
 .100 x .100 120pF Chip Capacitor
 .100 x .100 470pF Chip Capacitor
 100μF Electrolytic C3
- C4
- C5

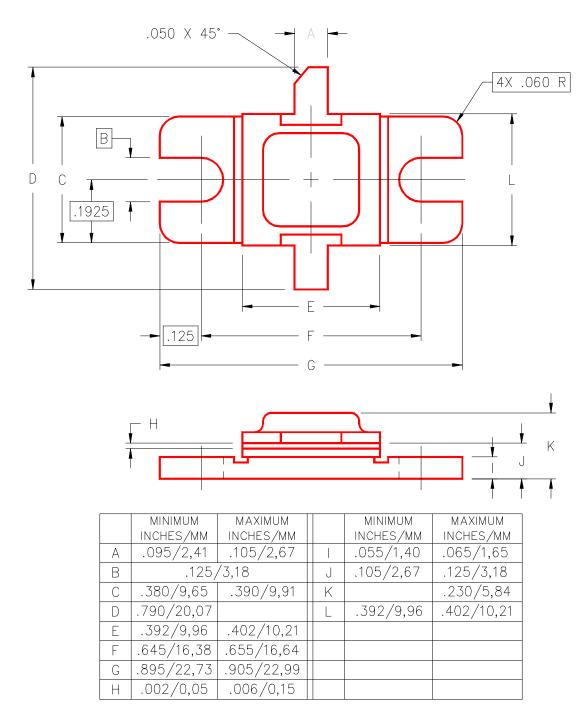
: #20 AWG L1

L2 : 3 Turns, #20 AWG Wound on #32 Drill Bit



PACKAGE MECHANICAL DATA

PACKAGE STYLE M138



Advanced Power Technology reserves the right to change, without notice, the specifications and information contained herein Visit our website at **WWW.ADVANCEDPOWER.COM** or contact our factory direct.